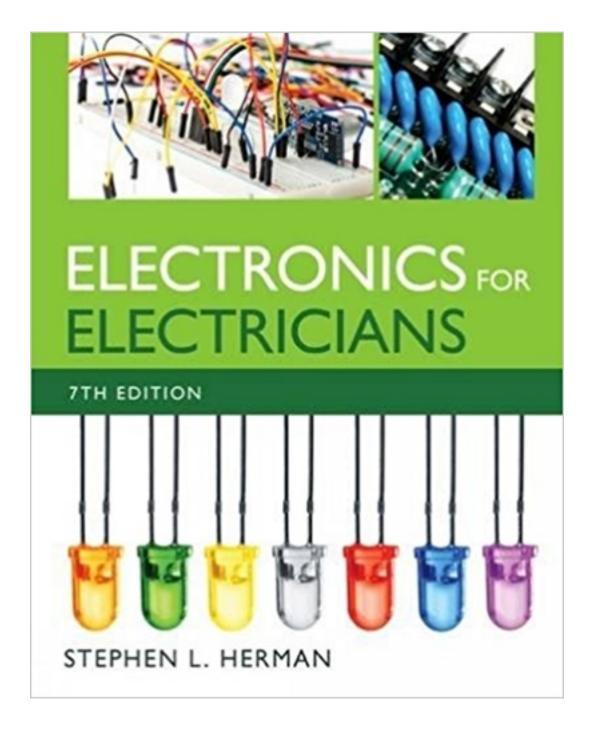
Test Bank for Electronics for Electricians 7th Edition by Herman

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Test Bank

Unit 2 — Power Rating and Heat Sinking Components

a. sodium oxide

ANS: D

ANS: A

b. magnesium peroxide

a. thermal compound

b. insulation compound

a. Insulation compound

between the device and the heat sink.

PTS: 1

PTS: 1

TRUE/FALSE				
1.	Heat sinks vary in size and shape, but have only one purpose.			
	ANS: T	PTS: 1	REF:	Heat Sinks
2.	The purpose of a heat sink is to decrease the surface area of the device connected to it.			
	ANS: F	PTS: 1	REF:	Heat Sinks
3.	The surface of the de	vice and heat sink may	y look p	erfectly flat to the naked eye.
	ANS: T	PTS: 1	REF:	Heat Sinks
4.	Using thermal compound when heat sinking components is not a necessity.			
	ANS: F	PTS: 1	REF:	Heat Sinks
5.	Small heat sinks are generally used when a component is operated at its lowest power rating.			
	ANS: F	PTS: 1	REF:	Heat Sinks
MUL'	ГІРЬЕ СНОІСЕ			
1.	Electrical and electro a. volts b. ohms	nic components have a	•	rating measured in watts amps
	ANS: C	PTS: 1	REF:	Power Rating
2.	The rating indica. power b. energy	cates the amount of hea	c.	ne component can dissipate before damage occurs resistance current
	ANS: A	PTS: 1	REF:	Power Rating
3.	The thermal compoun	nd that is greasy and ge	enerally	white in color is made from

c. beryllium perchlorate

c. resistance compound

d. break compound

c. Break compound

d. beryllium oxide

REF: Heat Sinks

REF: Heat Sinks

4. When a component is mounted to a heat sink, ____ is generally used to ensure a good thermal contact

5. ____ is used to fill in the gaps between the two surfaces and provide good thermal contact.

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b. Thermal compound d. Lock compound

ANS: B PTS: 1 REF: Heat Sinks